

Specification of Thermoelectric Module

TEC2-199-199-14

Description

The TEC2-199-199-14 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 199-199 couples module in size of 40 mm × 40 mm (top) / 40 mm × 40 mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

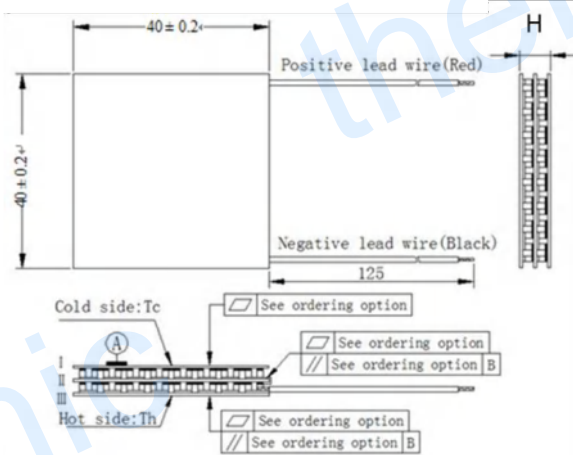
Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	93	104	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	24.5	26.6	Voltage applied to the module at DT _{max}
I _{max} (amps)	14.2	14.2	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	139.0	148.7	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.8	2.0	The module resistance is tested under AC
Tolerance	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 5.8 ± 0.2	0: Face II 0.08/0.08, Face III 0.08/0.08	125 ± 3 / Specify
TF	1: 5.8 ± 0.1	1: Face II 0.03/0.03, Face III 0.03/0.03	125 ± 3 / Specify

Eg. TF01: Thickness 5.8 ± 0.2 (mm) and Flatness Face II 0.03/0.03, Face III 0.03/0.03 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

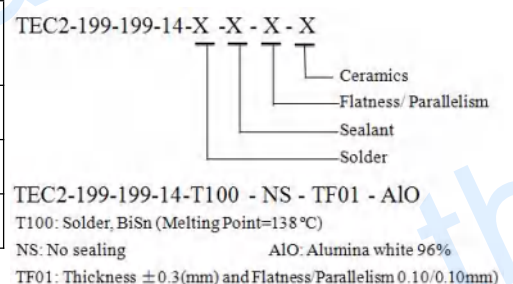
B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

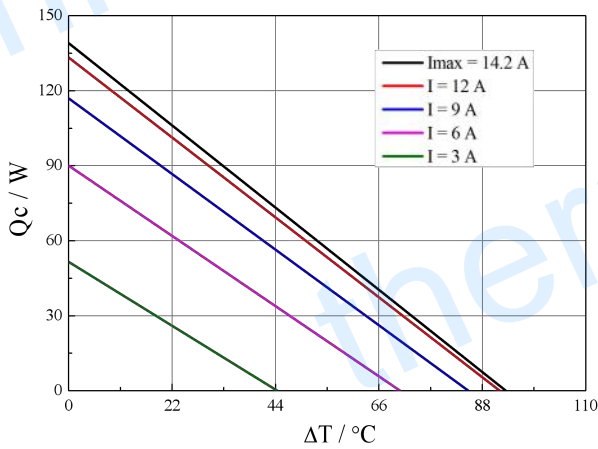
Naming for the Module



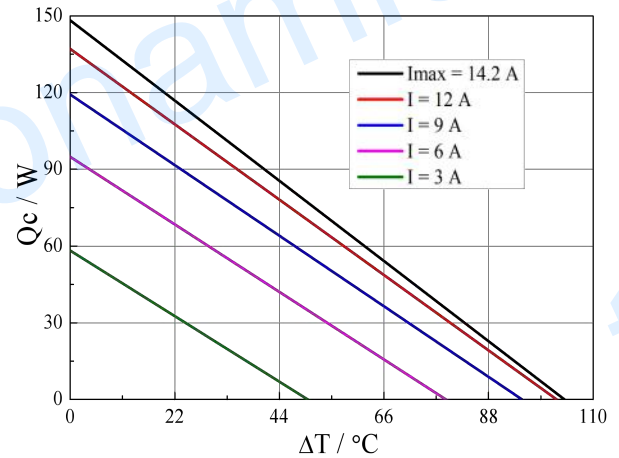
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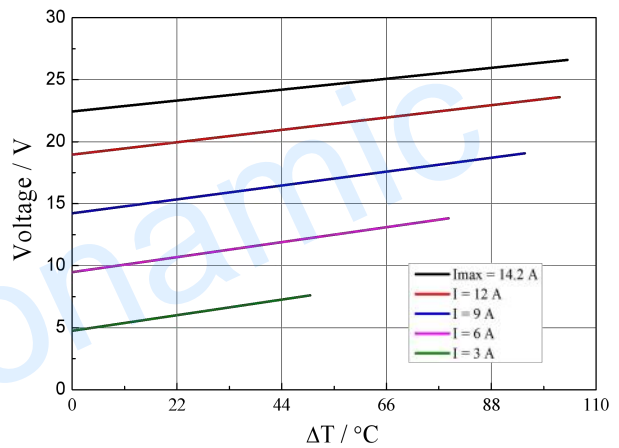
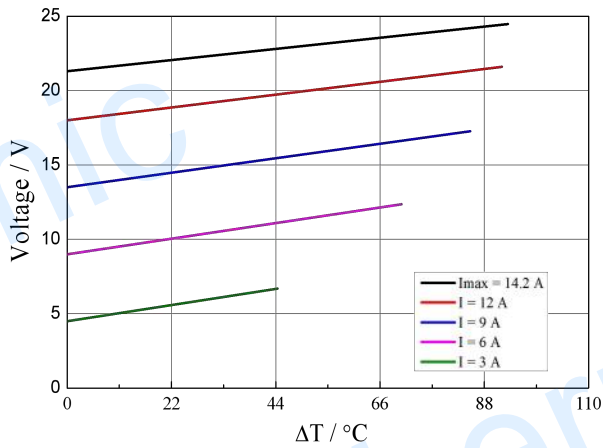
Performance Curves at Th=27 °C



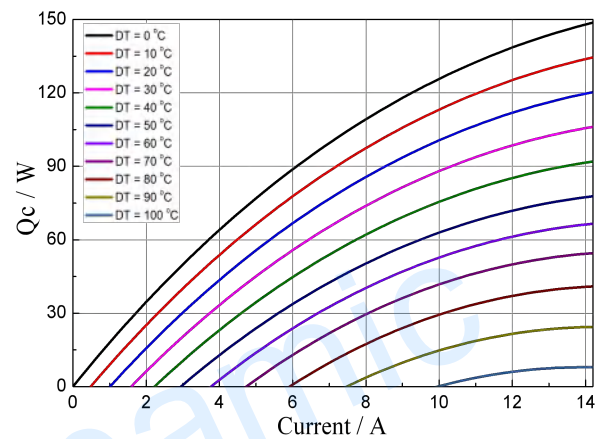
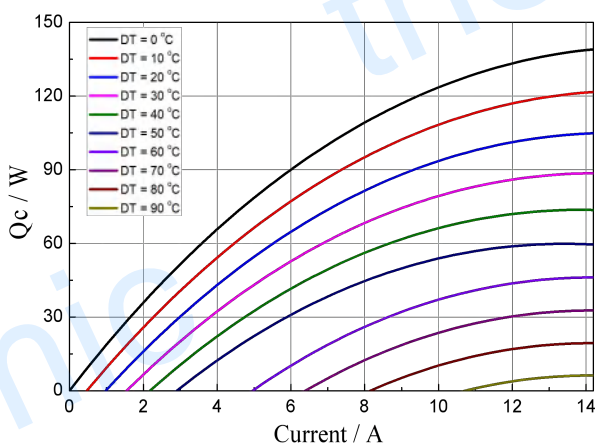
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(\Delta T)$



Standard Performance Graph $V = f(\Delta T)$



Standard Performance Graph $Q_c = f(V)$

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C

- Operation below I_{max} or V_{max}
- Work under DC